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A diagram illustrating a broadband microstrip-to-microstrip vertical via interconnection. The top part shows a 3D perspective of a microstrip line on a substrate with a vertical via. The middle part is a cross-sectional view showing the via structure with labels:  $r_{shield}$ ,  $r_{signal}$ ,  $r_{pad}$ ,  $r_{ground}$ ,  $r_{signal\_pad}$ ,  $r_{loop}$ , and  $W$ . The bottom part shows a top-down view of the microstrip lines and the via structure.

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A Broadband Microstrip-to-Microstrip Vertical  
Via Interconnection for Low Temperature Co-  
Fired Ceramic Applications

